Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	2979	(thermal or stress or buffer$6 or barrier or epoxy or resin or complian$6) with corner with (chip or die or IC or (integrated circuit) or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 12:33
L5	2786	4 and (@ad<"20031120" or @rlad<"20031120")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 12:33
L6	495	5 and (encapsula$6 or underfill$6 or overfill$6 or ((under or over) adj fill$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 12:34

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	26068	(thermal or stress or buffer$6 or barrier or epoxy or resin or complian$6) same (CTE or (coefficient near3 thermal near3 expans$6)) same (chip or die or IC or (integrated circuit) or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 13:49
L8	24252	7 and (@ad<"20031120" or @rlad<"20031120")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 13:48
L9	5294	8 and (encapsula$6 or underfill$6 or overfill$6 or ((under or over) adj fill$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 13:48
L10	17248	(thermal or stress or buffer$6 or barrier or epoxy or resin or complian$6) with (CTE or (coefficient near3 thermal near3 expans$6)) with (chip or die or IC or (integrated circuit) or semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 13:49
L11	3965	9 and 10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/11 13:49